L Number	Hits	Search Text	DB	Time stamp
1	2690	257/751.ccls. 257/752.ccls. 257/759.ccls. 257/760.ccls.	USPAT;	2004/11/05 11:52
-		257/762.ccls.	US-PGPUB	
2	522	(msq (methyl adj silsesquioxane)) and ((barrier with (dielectric	USPAT;	2004/11/05 11:56
_		insulator carbide nitride oxide oxynitride)) electromigration	US-PGPUB;	
		diffusion)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
3	304	((polymeric adj alkyl adj siloxane) sicoh sioch (polymeric adj	USPAT;	2004/11/05 12:46
		silicon adj carbide) "sic(h)") and ((barrier with (dielectric	US-PGPUB;	
	•	insulator carbide nitride oxide oxynitride)) electromigration	EPO; JPO;	
		diffusion)	DERWENT;	
		,	IBM_TDB	,
4	83	((polymeric adj alkyl adj siloxane) sioch sicoh) and ((polymeric adj silicon adj carbide) "sic(h)")	USPAT;	2004/11/05 13:04
			US-PGPUB;	,
			EPO; JPO;	
			DERWENT;	
		•	IBM_TDB	
5	39	(257/751.ccls. 257/752.ccls. 257/759.ccls. 257/760.ccls.	USPAT;	2004/11/05 13:07
		257/762.ccls.) and ((polymeric adj alkyl adj siloxane) sicoh	US-PGPUB;	
		sioch (polymeric adj silicon adj carbide) "sic(h)")	EPO; JPO;	
		,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	DERWENT;	
	ĺ		IBM_TDB	
6	323	(257/\$.ccls. 438/\$.ccls.) and ((polymeric adj alkyl adj siloxane)	USPAT;	2004/11/05 13:10
		sicoh sioch sich (polymeric adj silicon adj carbide) "sic(h)")	US-PGPUB;	
		,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
7	47	MIKAGI-K MIKAGI-KAORU	USPAT;	2004/11/05 13:23
			US-PGPUB;	
		·	EPO; JPO;	
		•	DERWENT	1
8	49	(257/751.ccls. 257/752.ccls. 257/759.ccls. 257/760.ccls.	USPAT;	2004/11/05 13:24
		257/762.ccls.) and ((silicon wafer semiconductor) and	US-PGPUB	
		(damascene inlaid "in-laid") and ((copper cu) same seed same		
		(electroplat\$3 plat43) same (cmp planar\$8)))		2004/44/05 42 25
9	53	(257/751.ccls. 257/752.ccls. 257/759.ccls. 257/760.ccls.	USPAT;	2004/11/05 13:25
1		257/762.ccls.) and (((dielectric insulat\$4 oxide dioxide sioch	US-PGPUB	
		sicoh sich "low-k" "low k") near4 barrier) with (reduc\$5 redox		
		deoxid\$7))		2004/44/05 42:27
10	22	((copper cu) near2 (plat\$6 electroplat\$6)) with (seed near2	USPAT;	2004/11/05 13:27
		(tan tin ((tantalum titanium) adj nitride)))	US-PGPUB	